NITTA DuPont INCORPORATED

Felt-based Polishing Pad

Suba™

Suba™ pad is foamed by non-woven felt which polyurethane is coagulated.

Suba™ shows excellent performance at stock polishing in silicon wafer, sapphire wafer and oxide material wafer.

Suba™ Series

Suba™ pad is designed for stock removal and semi-final process of silicon wafer polishing.

Also, it’s available for the edge and notch polishing of silicon wafer. There are many product lines to cover each process requirement.

☐ Advantages

1. High removal rate
2. Low defectivity
3. Excellent flatness

☐ SEM Image

Suba400

Suba600

Suba800

☐ Physical Properties

Product	Thickness (mm)	Hardness (Asker C)	Compressibility (%)
Suba™ 400	1.27	60	9.4
Suba™ 600	1.27	80	4.2
Suba™ 800	1.27	83	3.3
Suba™ 840	1.27	84	2.6
Suba™ 800M2	1.27	87	2.7

※ Suba™ is a trademark, service mark or registered trademark of affiliates of DuPont de Nemours, Inc.

※ The values such as a physical property indicated, show the standard value. The product specifications are not guaranteed.